

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.93914	8.0	3.5728
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.33305	8.8	3.93008
	Filler	Silica fused	60676-86-0	40.86858	83.0	37.0678
	Carbon Black	Carbon black	1333-86-4	0.09848	0.2	0.08932
			Subtotal	49.23925	100	44.66
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01742	0.04	0.0158
	Copper alloy	Iron (Fe)	7439-89-6	0.04355	0.1	0.0395
	Copper alloy	Copper (Cu)	7440-50-8	43.4892	99.86	39.4447
			Subtotal	43.55017	100	39.5
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.02536	100.0	0.93
			Subtotal	1.02536	100	0.93
Die	Doped Silicon	Silicon (Si)	7440-21-3	2.28225	100.0	2.07
			Subtotal	2.28225	100	2.07
Clip Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00064	0.04	0.00058
	Copper alloy	Iron (Fe)	7439-89-6	0.00159	0.1	0.00144
	Copper alloy	Copper (Cu)	7440-50-8	1.58543	99.86	1.43798
			Subtotal	1.58766	100	1.44
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.11577	5.0	0.105
	Lead alloy	Silver (Ag)	7440-22-4	0.05788	2.5	0.0525
	Lead alloy	Lead (Pb)	7439-92-1	2.14168	92.5	1.9425
			Subtotal	2.31533	100	2.1
Total				100.00002	100	90.7

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.